

■ Application

Control equipment controlling heat excessively generated within the chamber in the semiconductor manufacturing process, and maintaining temperature by selecting from low to high temperature.

■ Applied fields

Etching, CVD

■ General Features

- ▶ Heat energy storage system
- ▶ Dynamic temperature coordination
- ▶ Energy savings
- ▶ Long MTBF
- ▶ Proximity control system



- ▶ Multi channel is used with one refrigeration system (option)
- ▶ Quick response time, minimum variation
- ▶ Small sized footprint

■ Utility Requirements

Item	Specification	
	Single	Duale
Dimension	270(W)×630(D)×750(H)	400(W)×630(D)×800(H)
Temperature Range	1CH : -10°C ~ +50°C	2CH : -10°C ~ +50°C
Cooling Capacity	1CH : 2000 watts at -10 °C	2CH : 4000 watts at 10 °C
Coolant Flow Rate	20LPM	20LPM
Coolant Type	FC-3283	FC-3283
Electrical Spec	208V, 3P, 4W, 15A	208V, 3P, 4W, 30A
Temperature Accuracy	±0.1 °C	±0.1 °C